

1. Power supply selection (Note: \* default setting)

POWER SOURCE

	CN33
DC 5V	1-2
USB VBUS	2-3 *
JTAG V-SUPPLY	Open

VCC SELECTION

	CN29	CN34	CN35	CN36	CN37	CN40
3.3V	2-3 *	1-2 *	1-2 *	1-2 *	1-2 *	1-2 *
5V	2-3	2-3	2-3	1-2	1-2	1-2
JTAG V-supply	1-2	1-2	1-2	1-2	1-2	1-2

Note: CN40 should be OPEN when USB-less FM3 is used.

2. Switch, Jumper Pin Settings (Note: \* default setting)

	FUNCTION	SETTING	ACTION
SW1	RESET	PUSH ON	RESET
		PUSH OFF	NOT RESET
SW2	MD0	1-2	HIGH
		2-3 *	LOW
SW3	MD1	1-2	HIGH
		2-3 *	LOW
SW4	FM3 USB SELECTION	5-6    2-3	USB HOST
		4-5 *    1-2 *	USB DEVICE
CN5	CAN TRANSCEIVER MODE CONTROL	1-2 *	STANBY MODE
		2-3	HI-SPEED MODE
CN6	TX0_0 (CAN TX)	1-2	CONNECT TO CAN TRANSCEIVER
		2-3 *	OPEN
CN8	RX0_0(CAN RX)	1-2	CONNECT TO CAN TRANSCEIVER
		2-3 *	OPEN
CN9	CAN RX and TX CONNECTION	1-2	SHORT
		2-3 *	OPEN
CN10	SOT0_0 (UART TX)	1-2	CONNECT TO RS TRANSCEIVER
		2-3 *	OPEN
CN11	SIN0_0 (UART RX)	1-2	CONNECT TO RS TRANSCEIVER
		2-3 *	OPEN
CN13	MD1	1-2 *	CONNECT TO MD1 SWITCH
		2-3	OPEN

CN14	UDP0 (USB D+)	1-2	CONNECT TO USB CONNECTOR
		2-3 *	OPEN
CN16	UDP1 (USB D-)	1-2	CONNECT TO USB CONNECTOR
		2-3 *	OPEN
CN17	P50	1-2	CONNECT TO VBUS CONTROL IC FLG
		2-3 *	OPEN
CN18	P51	1-2	CONNECT TO VBUS CONTROL IC EN
		2-3 *	OPEN
CN19	P61	1-2	CONNECT TO USB D+ PULL-UP CONTROL
		2-3 *	OPEN
CN21	P60 (USB CONN. DET.)	1-2	CONNECT TO USB VBUS
		2-3 *	OPEN
CN22	TEST CONNECTOR	1-2 *	ALWAYS SET THIS
		2-3	DO NOT SET THIS
CN24	TEST CONNECTOR	N/A	DO NOT USE THIS CONNECTOR
CN25	TEST CONNECTOR	N/A	DO NOT USE THIS CONNECTOR
CN26	TDO	1-2 *	PULL-UP
		2-3	N/A
CN27	TCK	1-2 *	PULL-UP
		2-3	PULL-DOWN
CN28	XTRST	1-2 *	PULL-UP
		2-3	N/A
JP1	AVRH	1-2 *	CONNECT TO AVCC

Revision history:  
2012/07/04 Initial revision

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The following precautions apply to the product described in this manual.

Before moving the product, be sure to turn off all the power supplies and unplug the cables. Watch your step when carrying the product. Do not use the product in an unstable location such as a place exposed to strong vibration or a sloping surface.

Do not place anything on the product or expose the product to physical shocks. Do not carry the product after the power has been turned on. Doing so may cause a malfunction due to overloading or shock.

Since the product contains many electronic components, keep it away from direct sunlight, high temperature, and high humidity to prevent condensation. Do not use or store the product where it is exposed to much dust or a strong magnetic or electric field for an extended period of time. Inappropriate operating or storage environments may cause a fault.

Use the product within the ranges given in the specifications. Operation over the specified ranges may cause a fault.

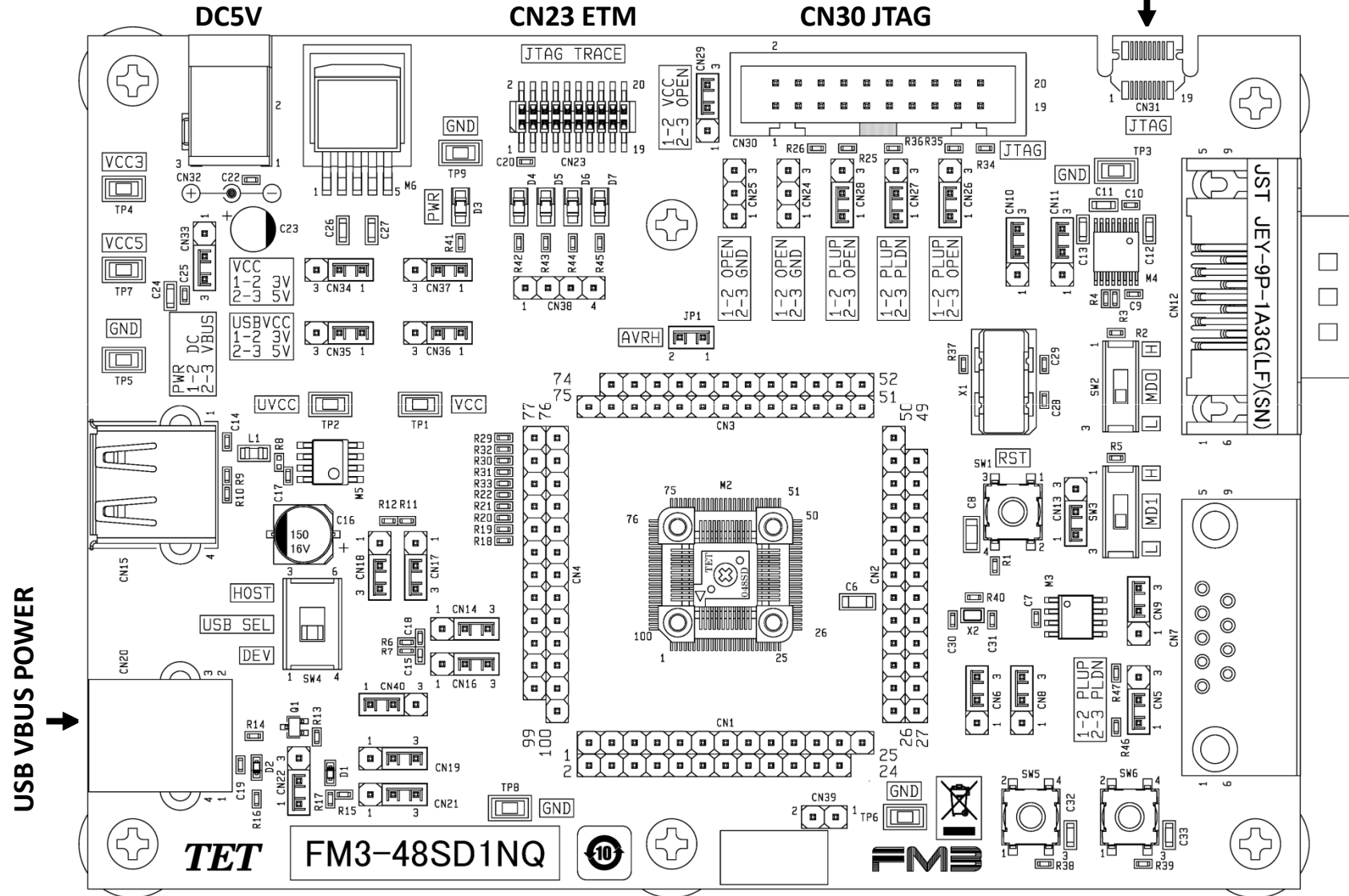
To prevent electrostatic breakdown, do not let your finger or other object come into contact with the metal parts of any of the connectors. Before handling the product, touch a metal object (such as a door knob) to discharge any static electricity from your body.

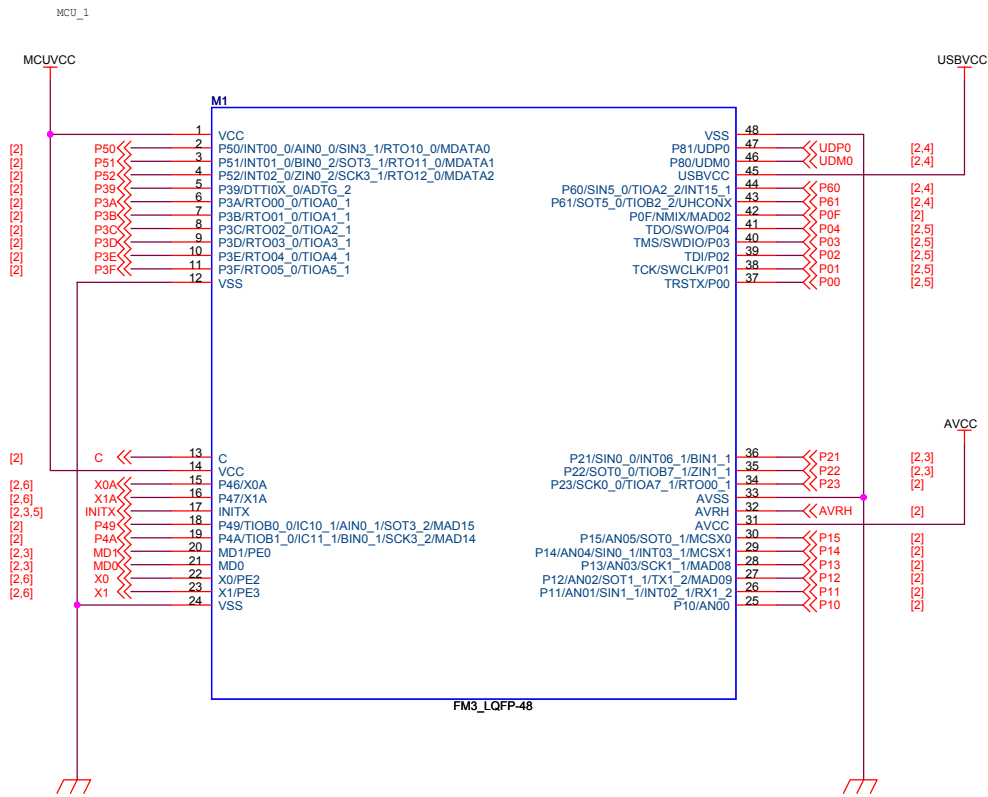
Always turn the power off before connecting or disconnecting any cables from the product. When unplugging a cable, unplug the cable by holding the connector part without pulling on the cable itself. Pulling the cable itself or bending it may expose or disconnect the cable core, resulting in a fault.

It is recommended that it be stored in the original packaging. Transporting the product may cause a damage or fault. Therefore, keep the packaging materials and use them when re-shipping the product.

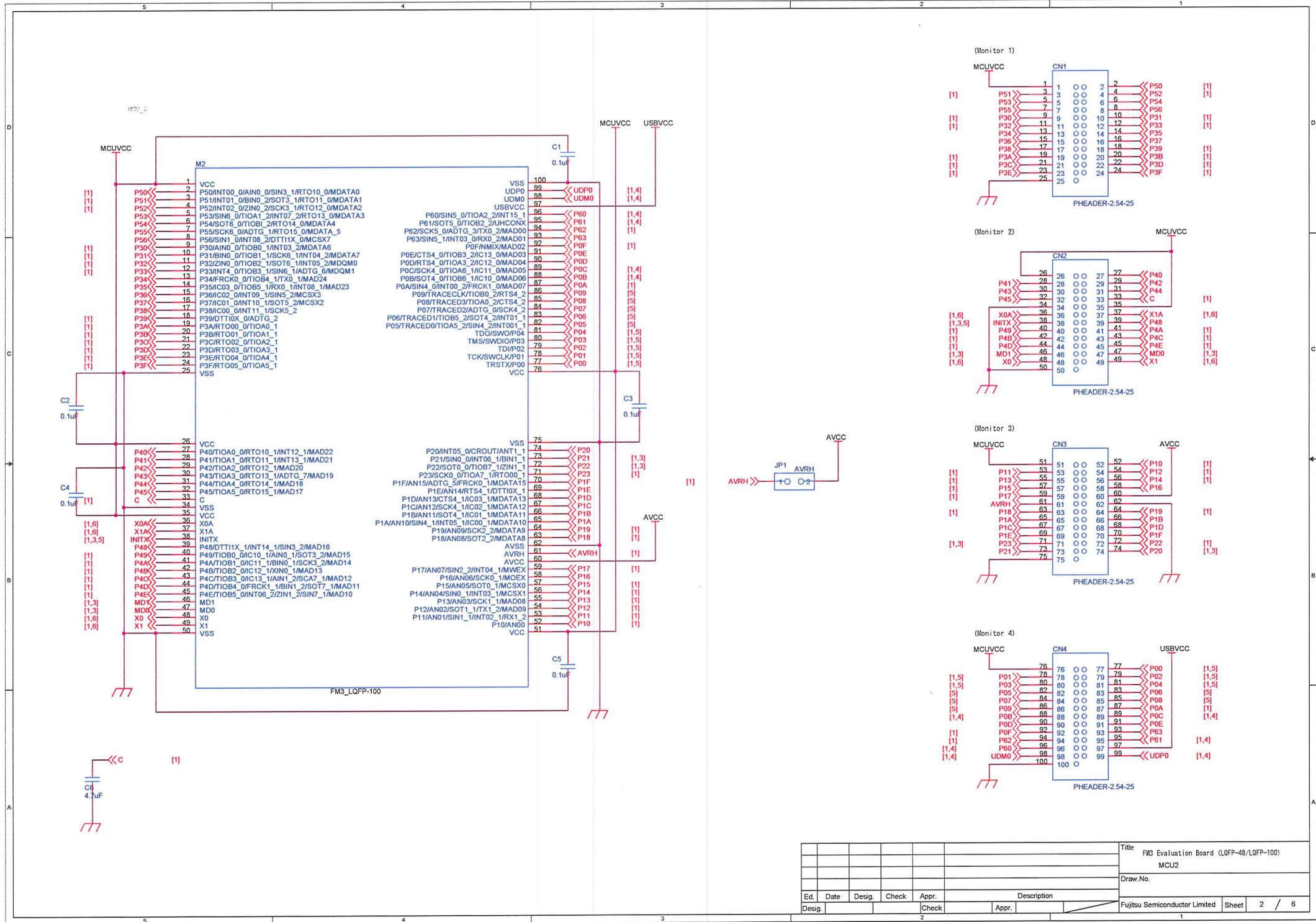
**FM3-48SD1NQ (FIGURE EXAMPLE BELOW)**  
**FM3-100SD1NQ**

**CN26 JTAG**  
**TET SICA20C20Y-GA101**  
**(NOT MOUNTED)**

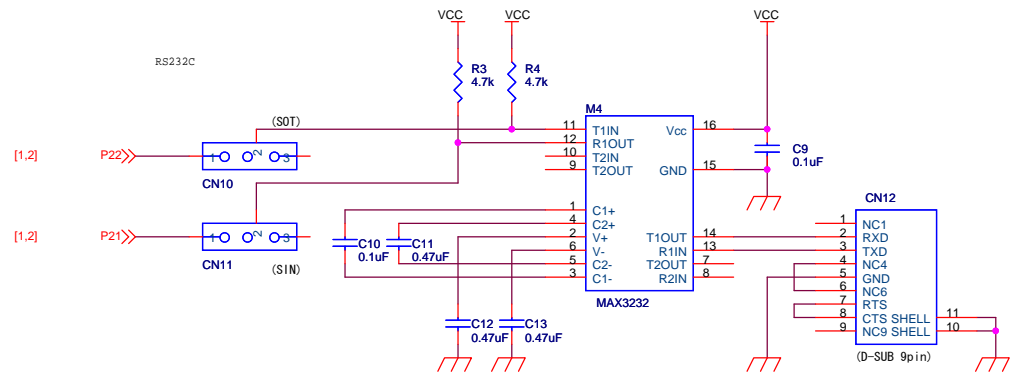
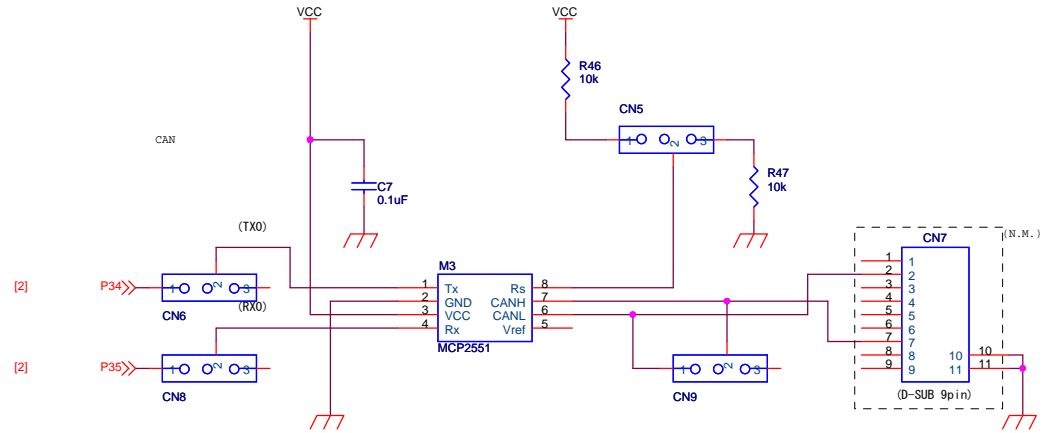
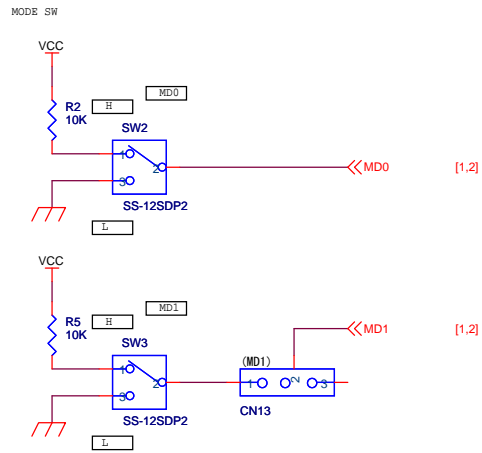
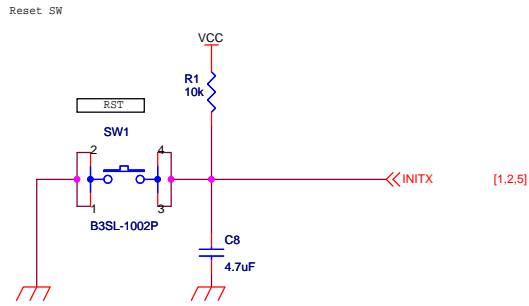




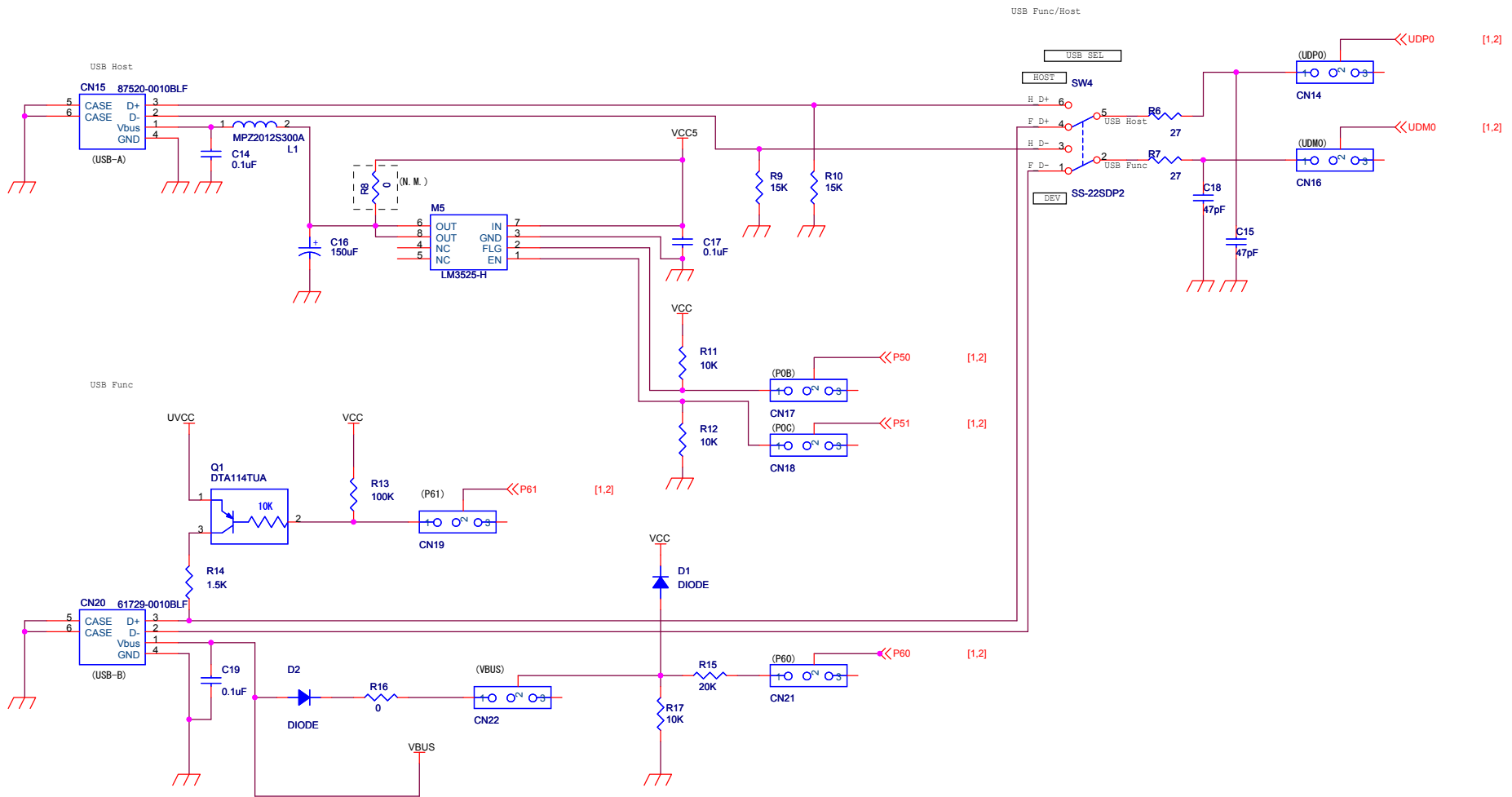
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Desig.			Check	Appr.	Fujitsu Semiconductor Limited				
								Sheet	1 / 6



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Desig.			Check	Appr.				
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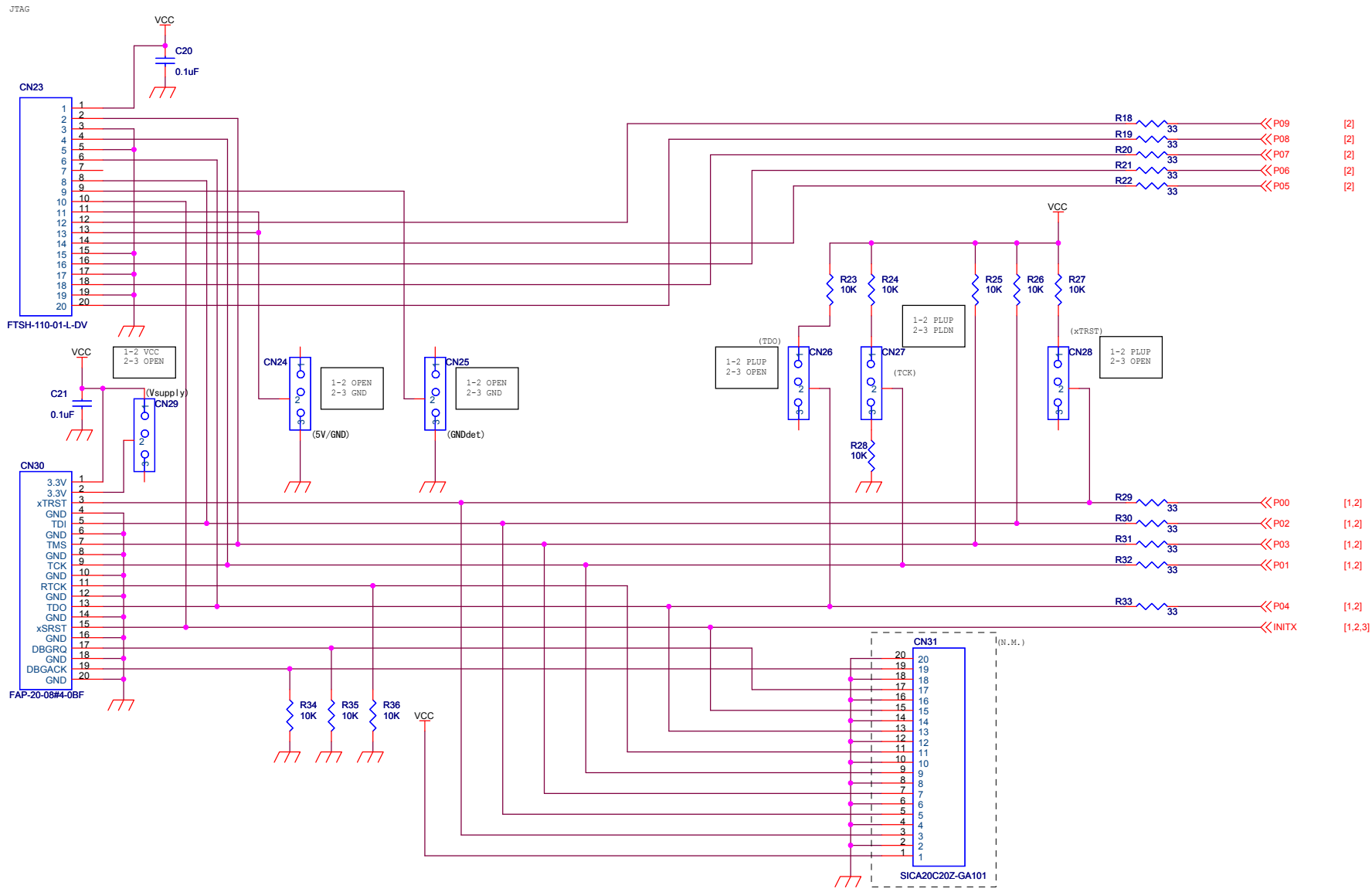


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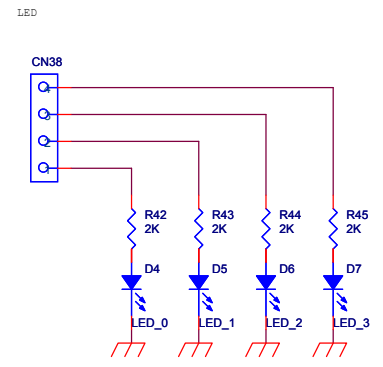
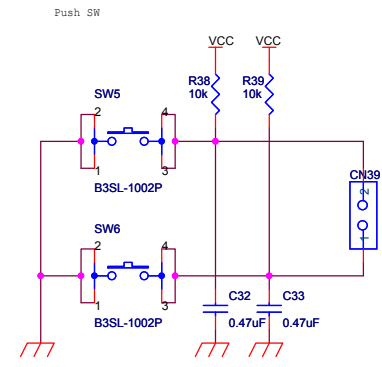
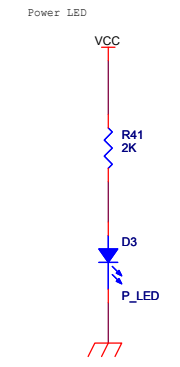
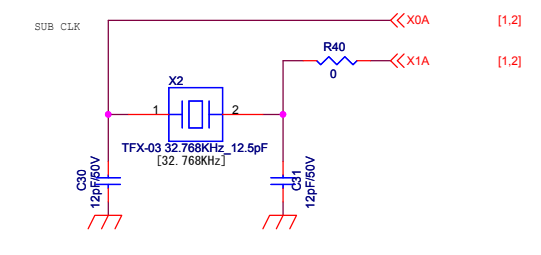
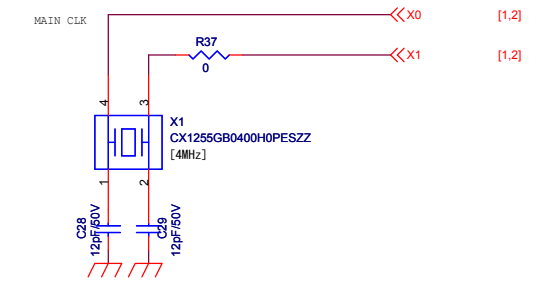
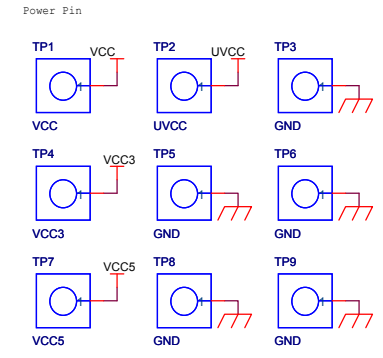
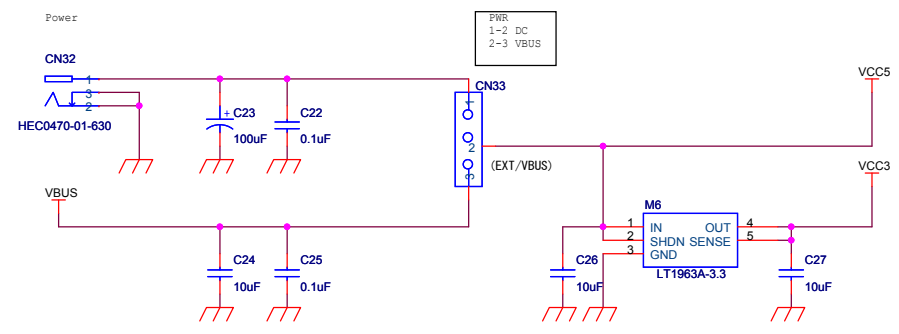


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							Fujitsu Semiconductor Limited	Sheet 4 / 6





				Title		FM3 Evaluation Board (LOFP-48/LOFP-100)	
				JTAG			
				Draw.No.			
Ed.	Date	Desig.	Check	Appr.	Description		
Desig.		Check		Appr.			
						Fujitsu Semiconductor Limited	Sheet 5 / 6



					Title		FM3 Evaluation Board (LOFP-48/LOFP-100)	
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Ed.	Date	Desig.	Check	Appr.	Description			
Desig.			Check	Appr.	Fujitsu Semiconductor Limited			
							Sheet	6 / 6

中華人民共和国「電子情報製品汚染防止管理弁法」の対応

Compliance with Administration on the Control of Pollution Caused by Electronic Information Products of the People's Republic of China

电子信息产品污染控制管理办法（第 39 号）



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产品中有毒有害物质或元素的名称及含量

部件名称	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr (VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
印刷线路板	×	○	○	○	○	○
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